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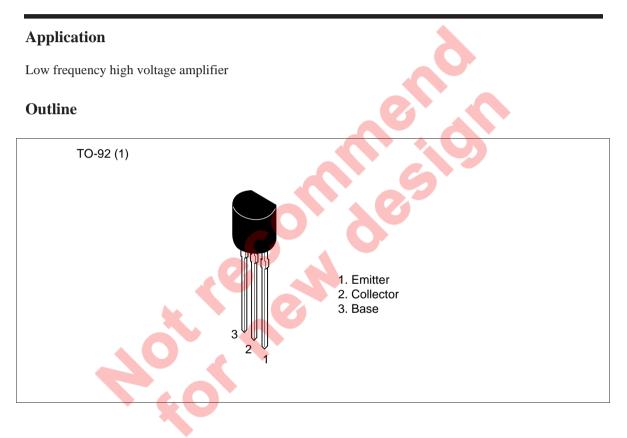
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Silicon NPN Epitaxial

RENESAS

ADE-208-1163 (Z) 1st. Edition Mar. 2001



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

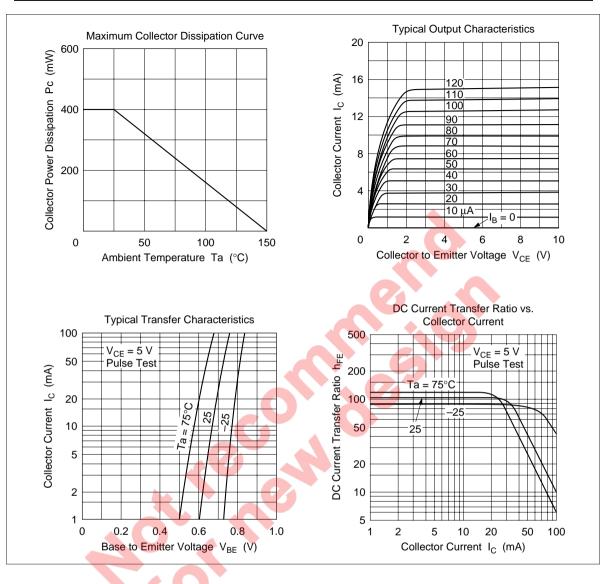
| Item | Symbol | 2SD2030 | 2SD2031 | Unit |
|------------------------------|------------------|-------------|-------------|------|
| Collector to base voltage | V _{CBO} | 160 | 200 | V |
| Collector to emitter voltage | V _{CEO} | 160 | 200 | V |
| Emitter to base voltage | V _{EBO} | 5 | 5 | V |
| Collector current | Ι _c | 100 | 100 | mA |
| Collector power dissipation | Pc | 400 | 400 | mW |
| Junction temperature | Tj | 150 | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | _55 to +150 | °C |

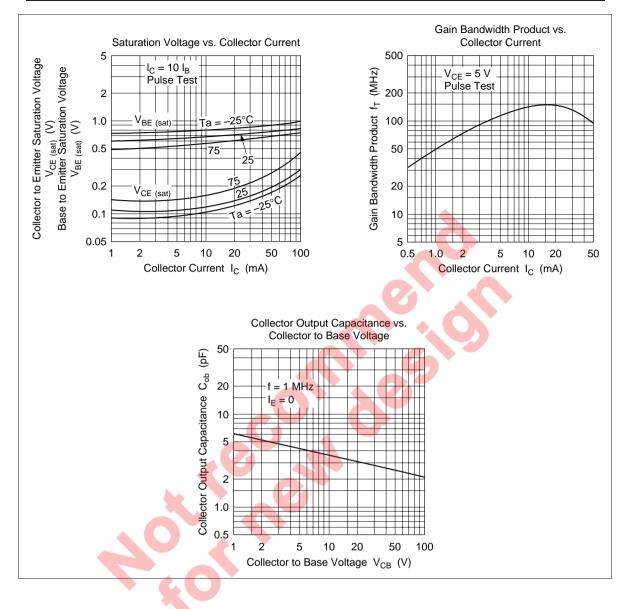
Electrical Characteristics (Ta = 25°C)

| | - | | - 3 | | | | |
|-----------------------------------------------------------------------|------------|----------------------|-----|-----|-----|------|-------------------------------------------------------|
| | | | | | | | 6 |
| Electrical Characteristics (Ta = 25°C) | | | | | | | |
| Item | | Symbol | Min | Тур | Max | Unit | Test conditions |
| Collector to base breakdown voltage | 2SD2030 | V _{(BR)CBO} | 160 | _ | 5 | V | $I_{c} = 10 \ \mu A, I_{E} = 0$ |
| | 2SD2031 | | 200 | | | | |
| Collector to emitter breakdown voltage | 2SD2030 | $V_{\rm (BR)CEO}$ | 160 | | - | V | $I_c = 1 \text{ mA}, R_{BE} = \infty$ |
| | 2SD2031 | _ | 200 | | | | |
| Emitter to base brea voltage | kdown | V _{(BR)EBO} | 5 | - | | V | $I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$ |
| Collector cutoff current | 2SD2030 | I _{CBO} | - | - | 10 | μΑ | $V_{CB} = 140 \text{ V}, I_{E} = 0$ |
| | 2SD2031 | _ | | | | | $V_{CB} = 160 \text{ V}, I_{E} = 0$ |
| DC current transfer ratio | | h _{FE1} *1 | 60 | _ | 200 | | $V_{ce} = 5 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$ |
| | | h _{FE2} | 30 | _ | _ | | $V_{ce} = 5 \text{ V}, \text{ I}_{c} = 1 \text{ mA}$ |
| Base to emitter volta | age | V _{BE} | _ | _ | 1.5 | V | $V_{ce} = 5 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$ |
| Collector to emitter s voltage | saturation | V _{CE(sat)} | | — | 0.5 | V | $I_{c} = 30 \text{ mA}, I_{B} = 3 \text{ mA}$ |
| Gain bandwidth proc | duct | f _T | | 140 | _ | MHz | $V_{ce} = 5 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$ |
| Collector output capacitance C _{ob} | | C _{ob} | | 3.8 | — | pF | $V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$ |
| Note: 1. The 2SD2030 and 2SD2031 are grouped by h_{FE1} as follows. | | | | | | | |
| Grade B | С | | | | | | |
| | 100 10 | | • | | | | |

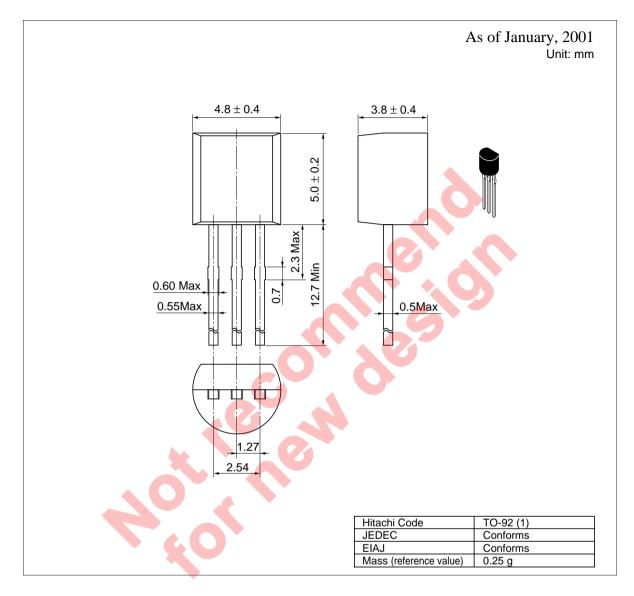
100 to 200 $\boldsymbol{h}_{\text{FE1}}$ 60 to 120







Package Dimensions



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